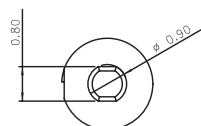
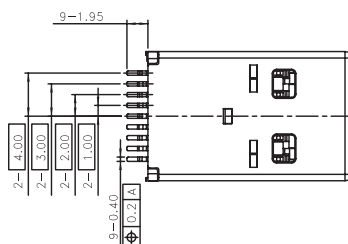
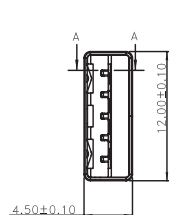
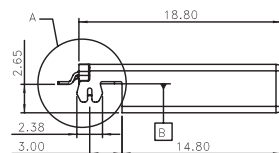
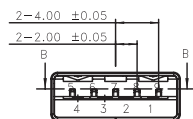
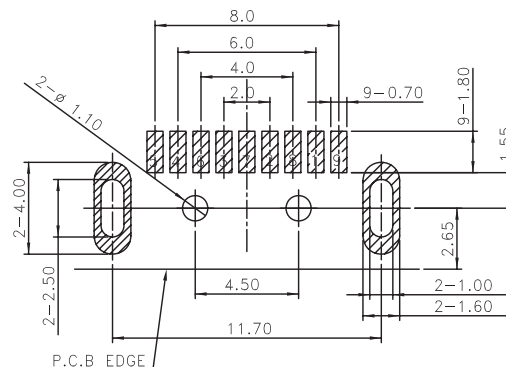
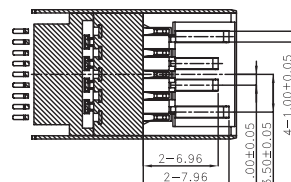


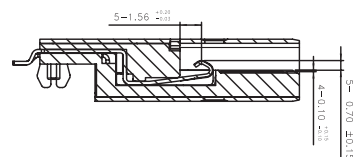
DETAIL A



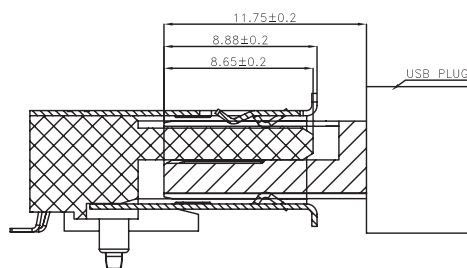
DETAIL B



PCB LAYOUT - COMPONENT VIEW



TRANSVERSAL CUTTING VIEWS



TECHNICAL CHARACTERISTICS

MATERIAL
 INSULATOR: LCP
 FLAMMABILITY RATING: UL94-V0
 COLOR: BLUE
 CONTACT MATERIAL: PHOSPHORE BRONZE
 CONTACT TYPE: STAMPED
 CONTACT PLATING: UNDERPLATE 1.27 to 2.54 µm Ni
 CONTACT AREA 0.76 µm Gold
 SOLDER TAIL AREA 2.54 to 5.08 µm Matt Tin
 SHIELDING: STEEL BRIGHT TIN PLATED
 QUALITY CLASS: 5000 MATING CYCLES

ENVIRONMENTAL
 OPERATING TEMPERATURE: -20°C up to +85°C
 COMPLIANCE: LEAD FREE & RoHS

ELECTRICAL
 CURRENT RATING:
 - PIN 1 & PIN 4 (Vbus & corresponding ground PIN) 1.8A MAX
 - OTHER PINS 0.25 A MAX
 WORKING VOLTAGE: 30 VAC
 DIELECTRIC WITHSTANDING VOLTAGE: 100 VAC/MIN
 INSULATION RESISTANCE: > 100 MΩ
 CONTACT RESISTANCE:
 - PIN 1 & PIN 4: 30mΩ MAX
 - OTHER PINS: 50mΩ MAX

STANDARD
 CERTIFIED: E323964

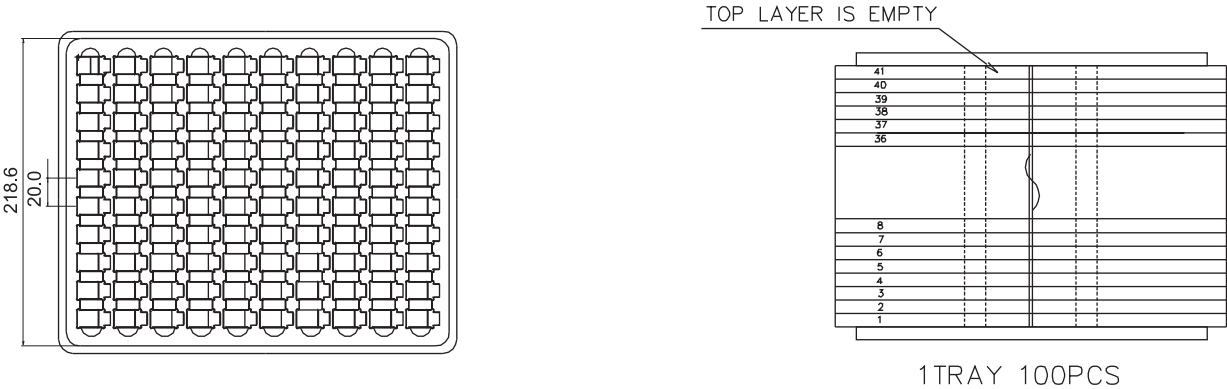
MECHANICAL
 INSERTION FORCE: 35.0N MAX
 EXTRACTION FORCE: 10.0N MIN

SOLDERING
 JEDEC LEAD FREE REFLOW SOLDERING

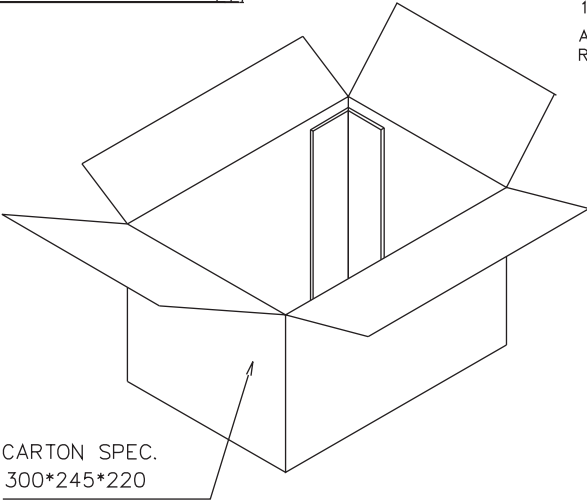
PACKAGING
 TRAY

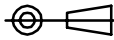

* NOTE: THE RECOMMENDED PCB LAYOUT IS FOR AN OPTIMIZED RETENTION FORCE OF CONNECTOR ON PCB BUT IT IMPLIES INSERTION FORCE THAT A LOT OF PICK AND PLACE MACHINES ARE NOT ABLE TO HANDLE. THEREFORE IT MIGHT BE NECESSARY TO DRILL BIGGER HOLES FOR THE CLIPS. PLEASE CHECK THIS CAREFULLY.

RoHS Compliant							SIZE
REV	DATE	FILE	BY	PROJECTION:	GENERAL TOLERANCE	DESCRIPTION: WR COM - USB 3.0 SMT PLUG WITH CLIP TYPE A	
G	30-JAN-15	GENERAL UPDATE	QL		.X = ± 0.2		A4
F	27-OCT-14	GENERAL UPDATE	AS		.XX = ± 0.15		
E	10-SEP-13	DIM & CHARAC	QL				
D	09-NOV-11	STENCIL	GG				
C	21-SEP-11	NOTE	GG	APPROVAL: NPr	UNIT: MM	WERI PART NO: 692 112 030 100	A4
B	10-MAY-11	UL	GG		SCALE:		
A	16-SEP-10	PDF	JP		SHEET: 1/4		
REV	DATE	FILE	BY		DRAW: AS		



NOTES
1. MATERIALS: PS
All Material in According With The Rohs Environment
Related Substances List Controlled.



RoHS Compliant								
G				PROJECTION: 	GENERAL TOLERANCE .X = +/- 0.2 .XX = +/- 0.15			
F								
E								
D								
C				APPROVAL: NPr	UNIT: MM	DESCRIPTION: WR-COM - USB 3.0 SMT PLUG WITH CLIP TYPE A		SIZE A4
B					SCALE:			
A					SHEET: 2/4	WERI PART NO: 692 112 030 100		
REV	DATE	FILE	BY		DRAW: AS			

1

2

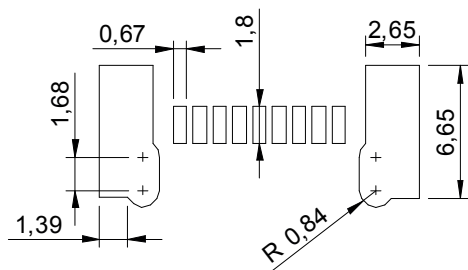
3

4

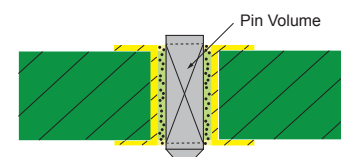
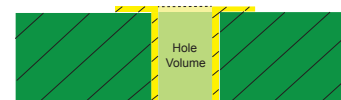
5

Stencil information for Through Hole Reflow soldering

PCB cross section



STENCIL LAYOUT * - COMPONENT VIEW



Free volume for solder paste

Theoretical Formula for Through Hole pins

Volume of the stencil aperture = (Hole volume - Pin volume) x 2

or

Volume of solder paste = (Hole volume - Pin volume) x 2



Stencil

Stencil Thickness: 150 µm

PCB

PCB thickness: 1.6mm

* NOTE: SEE PCB LAYOUT PAGE 1/3 FOR MISSING DIMENSIONS

RoHS Compliant				* NOTE: SEE PCB LAYOUT PAGE 1/3 FOR MISSING DIMENSIONS			
G				<div>PROJECTION:</div> <div></div>	<div>GENERAL TOLERANCE</div> <div>.X = \pm 0.2</div> <div>.XX = \pm 0.15</div>	<div></div> <div>WÜRTH ELEKTRONIK</div>	
F							
E							
D							
C				APPROVAL: NPr	UNIT: MM	DESCRIPTION: WR-COM - USB 3.0 SMT PLUG WITH CLIP TYPE A	SIZE A4
B					SCALE:		
A					SHEET: 3/4	WERI PART NO: 692 112 030 100	
REV	DATE	FILE	BY		DRAW: AS		

